



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-21
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS3H100AFY	BA3E*ZCOPD5V	A	Z6IA	2016-06-21
	Amount	UoM	Unit type	ST ECOPACK Grade
	26.40	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFF	1.75X4.7X0.98	N/A	flat	
Comment	Package: SOD128-FLAT NEP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BASE*ZCOPD5V									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	1.168	mg	supplier	die	Silicon (Si)	7440-21-3		1.091	mg	934075	41326				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	7705	341				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	856	38				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1712	76				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.007	mg	5993	265				
				supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	5993	265				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	7705	341				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	856	38				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1712	76				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	8562	379				
				supplier	polymer die coating	Durimide	proprietary		0.029	mg	24829	1098				
				Leadframe	Copper and its alloys	9.476	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		9.462	mg	998523	358409
								supplier	Leadframe	Iron (Fe)	7439-89-6		0.011	mg	1161	417
supplier	Leadframe	Iron Phosphide (Fe2P)	1310-43-6						0.003	mg	317	114				
Leadframe clip	Copper and its alloys	2.524	mg	supplier	Leadframe Clip	Copper (Cu)	7440-50-8		2.461	mg	975040	93220				
				supplier	Leadframe Clip	Iron (Fe)	7439-89-6		0.059	mg	23376	2232				
				supplier	Leadframe Clip	Zinc (Zn)	7440-66-6		0.003	mg	1189	114				
				supplier	Leadframe Clip	Iron Phosphide (Fe2P)	1310-43-6		0.001	mg	396	38				
Die Attach	Other organic materials	2.748	mg	JIG R	Solder Paste	Lead (Pb)	7439-92-1	7a-Lead in high me	2.611	mg	950146	98902				
				supplier	Solder Paste	Tin (Sn)	7440-31-5		0.137	mg	49854	5189				
Encapsulation	Other organic materials	10.189	mg	supplier	Molding Compound	Silica	60676-86-0		6.239	mg	612327	236326				
				supplier	Molding Compound	Epoxy Cresol Novolak	29690-82-2		1.678	mg	164687	63561				
				supplier	Molding Compound	Metal hydroxide	21645-51-2		1.343	mg	131809	50871				
				supplier	Molding Compound	Phenol resin	9003-35-4		0.895	mg	87840	33902				
Connection coating	Other inorganic materials	0.295	mg	supplier	Molding Compound	carbon black	1333-86-4		0.034	mg	3337	1288				
				supplier	Solder Alloy	Tin	7440-31-5		0.295	mg	1000000	11174				